

# Information note

INF223301

Dear

TOKYO ELECTRON DEVICE TELDEVICE cy-inside@teldevice.co.jp

With this Infineon Technologies AG Information Note we would like to inform you about the following

Change of packing method at all Amkor Technology Japan locations for legacy MCU products



On 16 April 2020, Infineon acquired Cypress. We are now in the process of merging and consolidating our tools and processes for (infineon + Secrements PCN, Information Notes, Errata and Product Discontinuance. For further details, please visit our website:

https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/

Cypress Semiconductor Corporation - An Infineon Technologies AG company, 198 Champion Court San Jose, CA 95134. Tel: (408) 943-2600



Products affected

Please refer to attached affected product list [1848]

### Detailed change information

- **Subject** Change of packing method from 2 pcs to 1 pc type for tray products and change of indicator from 1-point type to 3-points type for MCU products at all Amkor Technology Japan locations.
- **Reason** To standardize product box design across Infineon and eliminate restrapping activity in IFX Distribution Centers when a custom shipping label is attached to the MBB bag's surface.

For indicator at Amkor Technology Japan, it's standardization.

## Description Old New Packing method Packing method Product box design (2 pcs) Product box design (1 pc) Tray Inner box bottom Die cut box Tray Inner box top Self-lock design Size 360x165x80mm Size 400×180×110mm **HIC** indicator **HIC** indicator HumiJudge™ Cobalt free Humidity KYODOPRINTING CO., LTD. 1-point type 3-point type (30%RH) (5%, 10% and 60%RH)

## Product identification

#### Impact of change

Traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Infineon recommends that customers take this opportunity to review these changes against current process in receiving and storage since the change will align to Infineon shipping standard as we will move our Finished Goods inventory to Infineon's Distribution Centers in Singapore and Shanghai respectively.



The New product box (inner box) design will be introduced effective May 16, 2022 and during transition both old and new product box may be shipped.

Attachments

Affected product list [1848]

 Intended start of delivery

2022-10-19

If you have any questions, please do not hesitate to contact your local sales office.